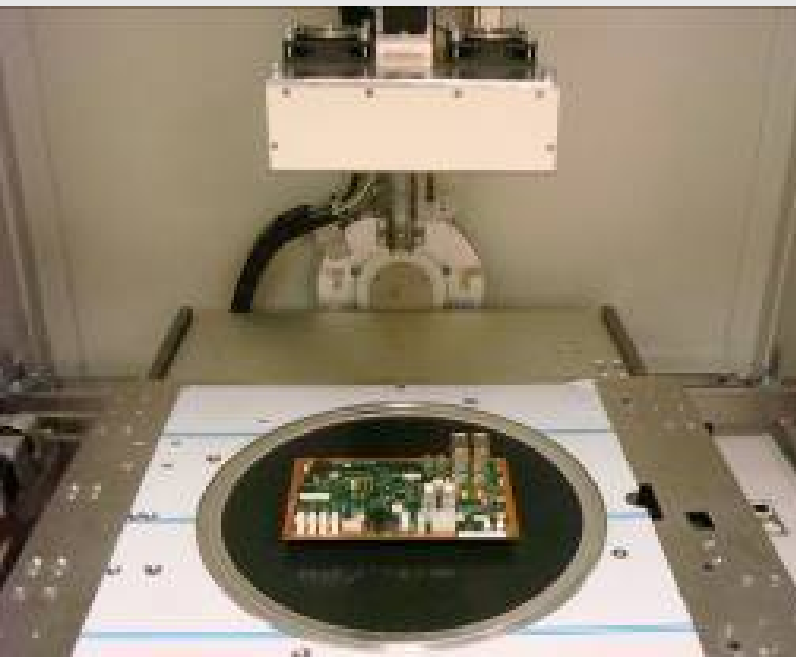


# X-Ray: 2D and 3D Capabilities



## Features

- Multi-focus tube with High Power, Nanofocus and Microfocus Capabilities; Open tube, enabling smaller spot size and higher spatial resolution down to 0.5  $\mu\text{m}$ .
- High power transmission target
- 10-160 kV
- 5-Motor driven axes
- 140+ degree oblique viewing via detector tilt
- 360 degree rotational sample table
- 2D and 3D-CT imaging
- Flat panel HD detector, 10~30 frames per second
- BGA analysis, Void calculations, Die attach analysis
- CNC capability



## Applications

- Non-destructive Failure analysis tool
- Inspection of IC components & solder joints on printed circuit boards
  - Typical defects: Cracks, Opens, Bridging, Voiding, Misalignment, Missing joints etc
- Inspection of active and passive components, electronic components and hybrid modules
- Checking electromechanical components, especially those that are fully enclosed, such as sensors, relays, safety fuses, coils etc.
- Inspection of plastics, ceramics, light metals and steel
- Evaluating Process effects on product reliability
- Root cause analysis of product failures from Usage or Test conditions